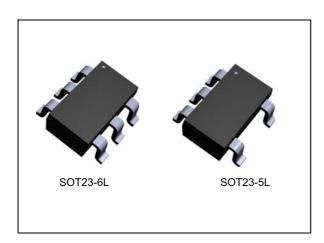
ESDAxxSCxY



Automotive quad-line Transil™ transient voltage suppressor (TVS) for ESD protection

Datasheet - production data



Features

- 4 unidirectional Transil functions
- 400 W peak pulse power (8/20 μs)

Benefits

- · High EOS and ESD protection levels
- · Suitable for high density boards
- · AEC-Q101 qualified

Complies with the following standards:

- ISO 10605: C = 150 pF, R = 330 Ω
 - 30 kV (air discharge)
 - 30 kV (contact discharge)
- ISO 10605: C = 330 pF, R = 330 Ω
 - 30 kV (air discharge)
 - 30 kV (contact discharge)
- ISO 7637-2

- Pulse 1: $V_S = -100 \text{ V}$

- Pulse 2a: $V_S = +50 \text{ V}$

- Pulse 3a: $V_S = -150 \text{ V}$

Pulse 3b: V_S = +100 V

Applications

Where ESD and EOS transient overvoltage protection in susceptible equipment is required, such as:

- Information entertainment
- · Signal communications
- Connectivity
- Comfort and convenience

Description

The ESDAxxSCxY devices are monolithic voltage suppressors designed to protect components which are connected to data and transmission lines against ESD.

They clamp the voltage just above the logic level supply for positive transients, and to a diode drop below ground for negative transient.

Figure 1. Pin configuration

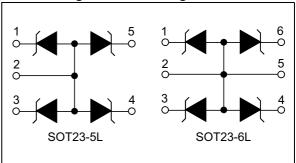


Table 1. Device summary

Order code	V _{BR} (min.)	Package
ESDA5V3SC6Y	5.3	SOT23-6L
ESDA6V1SC6Y	6.1	SOT23-6L
ESDA14V2SC5Y	14.2	SOT23-5L
ESDA14V2SC6Y	14.2	SOT23-6L
ESDA25SC6Y	25	SOT23-6L

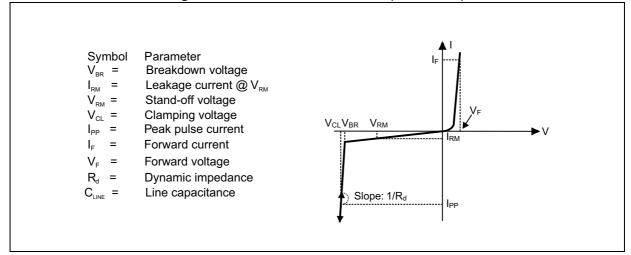
Characteristics ESDAxxSCxY

1 Characteristics

Table 2. Absolute ratings ($T_{amb} = 25 \, ^{\circ}C$)

Symbol	F	Parameter	Value	Unit
V _{PP}	Peak pulse voltage	ISO10605 (C = 150 pF, R = 330 Ω) Contact discharge Air discharge ISO10605 (C = 330 pF, R = 330 Ω) Contact discharge Air discharge	30 30 30 30	kV
P _{PP}	Peak pulse power (8/20µs)	ESDA5V3SC6Y, ESDA6V1SC6Y ESDA14V2SC5Y, ESDA14V2SC6Y,	300 400	W
		ESDA25SC6Y ESDA5V3SC6Y		
I _{PP}	Peak pulse current (8/20µs)	ESDA6V1SC6Y ESDA14V2SC5Y, ESDA14V2SC6Y ESDA25SC6Y	18 14 9	Α
T _j	Operating junction temperature range		-40 to +150	°C
T _{stg}	Storage temperature range	-65 to +150	°C	
T _L	Maximum lead temperature for s	260	°C	

Figure 2. Electrical characteristics (definitions)



ESDAxxSCxY Characteristics

Table 3. Electrical	characteristics - values	$(T_{amb} = 25 ^{\circ}C)$
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	\	/ _{BR} at I _R		I _{RM} at V _{RM}		V _{CL} at I _{pp} ⁽¹⁾		V _F at I _F		α T ⁽²⁾	C _{line}
Order code	min.	max.		max.		max.		max.		max.	typ.
	V	V	mA	μΑ	٧	V	Α	V	mA	10 ⁻⁴ /C	pF
ESDA5V3SC6Y	5.3	5.9	1	2	3	21	22	1.25	200	5	320
ESDA6V1SC6Y	6.1	7.2	1	2	5.2	19	18	1.25	200	6	190
ESDA14V2SC5Y, ESDA14V2SC6Y	14.2	15.8	1	5	12	35	14	1.25	200	10	100
ESDA25SC6Y	25	30	1	1	24	51	9	1.2	10	10	60

- 1. 8/20 µs waveform
- 2. $\Delta V_{BR} = \alpha T^* (T_{amb} 25 \, ^{\circ}C) \, ^{*}V_{BR} (25 \, ^{\circ}C)$

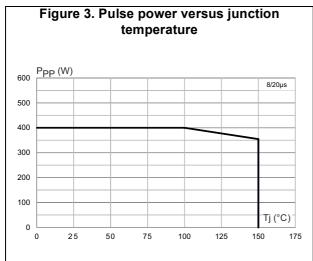
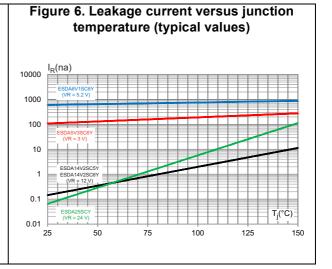


Figure 4. Peak pulse power versus exponential pulse duration (typical values)



Characteristics **ESDAxxSCxY**

Note:

ISO7637-2 pulse responses are not applicable for products with a breakdown voltage lower than the average battery voltage (13.5 V) like ESDA6V1SC6Y.

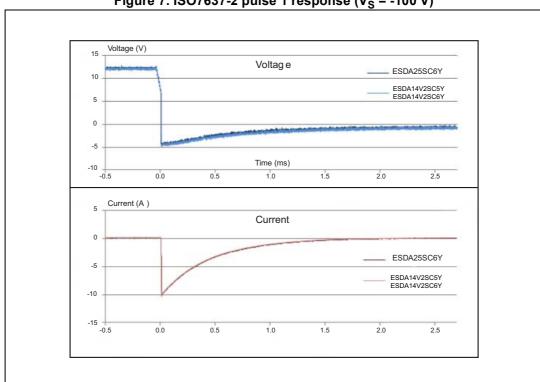
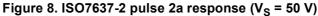
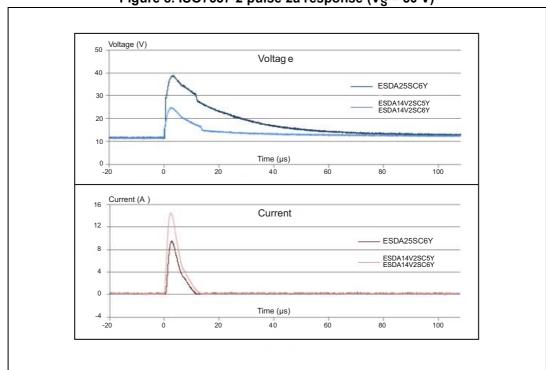


Figure 7. ISO7637-2 pulse 1 response ($V_S = -100 \text{ V}$)





ESDAxxSCxY Characteristics

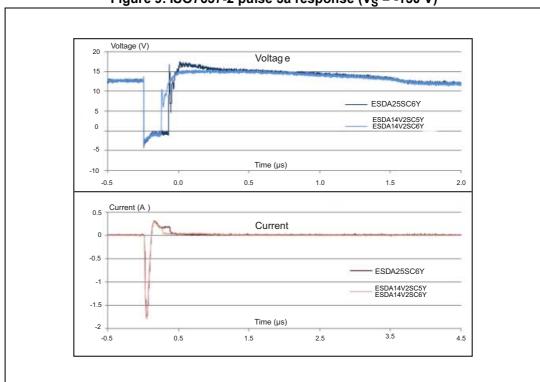
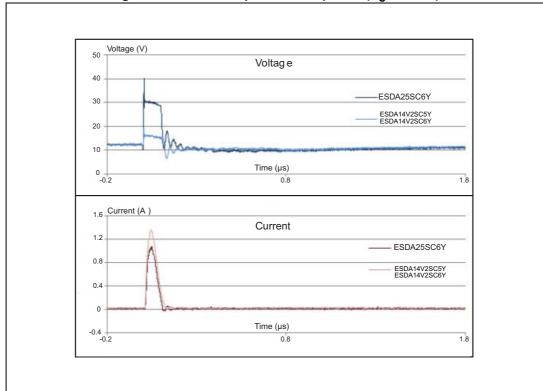


Figure 9. ISO7637-2 pulse 3a response ($V_S = -150 \text{ V}$)





2 Application and design guidelines

More information is available in the STMicroelectronics Application note AN2689: "Protection of automotive electronics from electrical hazards, guidelines for design and component selection".



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3 Package information

- Epoxy meets UL94, V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.



Package information ESDAxxSCxY

3.1 SOT23-5L package information

E e e A A2

Figure 11. SOT23-5L package outline

Table 4. SOT23-5L package mechanical data

			Dime	nsions		
Ref.		Millimeters			Inches	
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	0.90		1.45	0.0354		0.0570
A1	0		0.15	0		0.0059
A2	0.90		1.30	0.0354		0.0511
b	0.30		0.50	0.0118		0.0196
С	0.09		0.20	0.0035		0.0078
D	2.80		3.05	0.1102		0.1200
Е	1.50		1.75	0.0590		0.0688
е		0.95			0.0374	
Н	2.60		3.00	0.1023		0.1181
L	0.30		0.60	0.0118		0.0236
θ	0°		10°	0°		10°

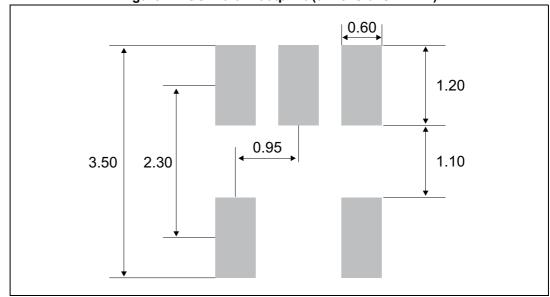


Figure 12. SOT23-5L footprint (dimensions in mm)

Package information ESDAxxSCxY

3.2 SOT23-6L package information

A E E e e

Figure 13. SOT23-6L package outline

Table 5. SOT23-6L package mechanical data

			Dimer	nsions		
Ref.		Millimeters				
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	0.90		1.45	0.0354		0.0570
A1	0		0.15	0		0.0059
A2	0.90		1.30	0.0354		0.0511
b	0.30		0.50	0.0118		0.0196
С	0.09		0.20	0.0035		0.0078
D	2.80		3.05	0.1102		0.1200
E	1.50		1.75	0.0590		0.0688
е		0.95			0.0374	
Н	2.60		3.00	0.1023		0.1181
L	0.30		0.60	0.0118		0.0236
θ	0°		10°	0°		10°

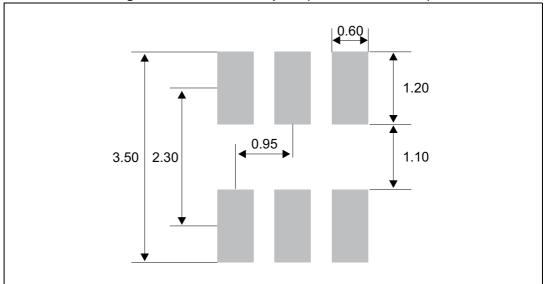


Figure 14. SOT23-6L footprint (dimensions in mm)



Recommendation on PCB assembly 4

4.1 Solder paste

- Use halide-free flux, qualification ROL0 according to ANSI/J-STD-004.
- "No clean" solder paste recommended.
- Offers a high tack force to resist component displacement during PCB movement.
- Use solder paste with fine particles: powder particle size 20-45 µm.

4.2 **Placement**

- Manual positioning is not recommended.
- It is recommended to use the lead recognition capabilities of the placement system, not the outline centering.
- 3. Standard tolerance of ± 0.05 mm is recommended.
- 3.5 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
- To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
- For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

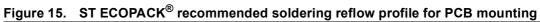
4.3 PCB design preference

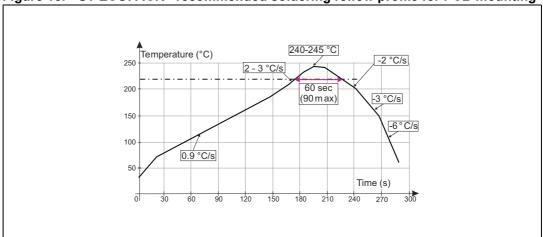
- To control the solder paste amount, the closed via is recommended instead of open vias
- The position of tracks and open vias in the solder area should be well balanced. The symmetrical layout is recommended, in case any tilt phenomena caused by asymmetrical solder paste amount due to the solder flow away.

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4.4 Reflow profile





Note: Minimize air convection currents in the reflow oven to avoid component movement.



Ordering information ESDAxxSCxY

5 Ordering information

Figure 16. Ordering information scheme

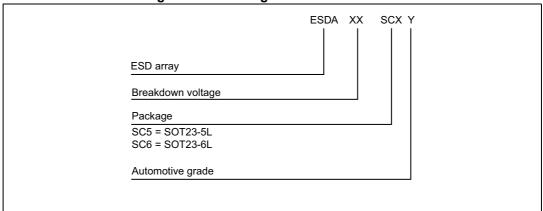


Table 6. Ordering information

Order codes	Marking ⁽¹⁾	Package	Weight	Base qty	Delivery mode
ESDA5V3SC6Y	ES5Y	SOT23-6L	14 mg		
ESDA6V1SC6Y	ES6Y	SOT23-6L	14 1119		
ESDA14V2SC5Y	EC1Y	SOT23-5L	16 mg	3000	Tape and reel
ESDA14V2SC6Y	ES1Y	SOT23-6L	To mg		
ESDA25SC6Y	ES2Y	SOT23-6L	14 mg		

^{1.} The marking can be rotated by multiples of 90° to differentiate assembly location

6 Revision history

Table 7. Document revision history

Date	Revision	Changes
05-Oct-2015	1	Initial release.

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